

Kang-Yi Lin

List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/201742/publications.pdf>

Version: 2024-02-01

10
papers

221
citations

1307366

7
h-index

1372474

10
g-index

10
all docs

10
docs citations

10
times ranked

417
citing authors

#	ARTICLE	IF	CITATIONS
1	Effect of Surface Potential on NIH3T3 Cell Adhesion and Proliferation. Journal of Physical Chemistry C, 2014, 118, 14464-14470.	1.5	57
2	Effect of Surface Potential on Extracellular Matrix Protein Adsorption. Langmuir, 2014, 30, 10328-10335.	1.6	45
3	Achieving ultrahigh etching selectivity of SiO ₂ over Si ₃ N ₄ and Si in atomic layer etching by exploiting chemistry of complex hydrofluorocarbon precursors. Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films, 2018, 36, .	0.9	40
4	Effect of Surface Potential on the Adhesion Behavior of NIH3T3 Cells Revealed by Quartz Crystal Microbalance with Dissipation Monitoring (QCM-D). Journal of Physical Chemistry C, 2017, 121, 533-541.	1.5	32
5	Selective atomic layer etching of HfO ₂ over silicon by precursor and substrate-dependent selective deposition. Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films, 2020, 38, .	0.9	16
6	Improvement of the gas cluster ion beam-(GCIB)-based molecular secondary ion mass spectroscopy (SIMS) depth profile with O ₂ ⁺ cosputtering. Analyst, The, 2016, 141, 2523-2533.	1.7	9
7	Assessment of the Effects of Surface Potential on the Kinetics of HEK293T Cell Adhesion Behavior Using a Quartz Crystal Microbalance with Dissipation Monitoring. Journal of Physical Chemistry C, 2018, 122, 694-704.	1.5	9
8	Enhancing the Sensitivity of Molecular Secondary Ion Mass Spectrometry with C ₆₀ ⁺ -O ₂ ⁺ Cosputtering. Analytical Chemistry, 2013, 85, 3781-3788.	3.2	7
9	Significance of plasma-photoresist interactions for atomic layer etching processes with extreme ultraviolet photoresist. Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films, 2020, 38, .	0.9	4
10	Ag Electromigration Against Electron Flow in Sn5Ag/Cu Solder Bump. Electrochemical and Solid-State Letters, 2009, 12, H445.	2.2	2